

Title (en)

Aqueous solution for forming metallic complex, tin-silver alloy plating solution, and method of plating with said plating solution

Title (de)

Wässrige Lösung zur Herstellung von Metallkomplexen, Beschichtungslösung für Zinn-Silber-Legierungen und Verfahren zur Beschichtung mit dieser Lösung

Title (fr)

Solution aqueuse pour la formation des complexes métalliques, solution de placage d'un alliage étain-argent, et procédé de placage avec celui-ci

Publication

EP 0893514 A3 19990728 (EN)

Application

EP 98115964 A 19970130

Priority

- EP 97901777 A 19970130
- JP 3749696 A 19960130
- JP 7524596 A 19960304

Abstract (en)

[origin: EP0893514A2] In the present invention, the tin-silver alloy plating solution comprising: a tin compound; a silver compound; and a complexing agent including a pyrophosphoric compound and an iodic compound. Therefore, the tin-silver alloy layer, whose composition can be optionally designed, can be formed, with high electric current efficiency, without using harmful compound: cyanide. The plating solution can resist to an air-stir; the plating solution is very stable; an external shape, adhesivity, solder-wettability of the tin-silver alloy layer are satisfactory; and the alloy is an advantageous alloy for solder plating.

IPC 1-7

C25D 3/60; **C25D 3/64**

IPC 8 full level

C25D 3/60 (2006.01); **C25D 3/64** (2006.01); **H01L 23/485** (2006.01); **H01L 23/498** (2006.01); **H05K 3/24** (2006.01); **H05K 3/34** (2006.01)

CPC (source: EP KR US)

C25D 3/56 (2013.01 - KR); **C25D 3/60** (2013.01 - EP US); **C25D 3/64** (2013.01 - EP US); **H01L 23/49866** (2013.01 - EP US); **H01L 24/10** (2013.01 - EP US); **H01L 24/13** (2013.01 - EP US); **H01L 2224/03912** (2013.01 - EP US); **H01L 2224/0401** (2013.01 - EP US); **H01L 2224/13** (2013.01 - EP US); **H01L 2224/13099** (2013.01 - EP US); **H01L 2924/01006** (2013.01 - EP US); **H01L 2924/01011** (2013.01 - EP US); **H01L 2924/01019** (2013.01 - EP US); **H01L 2924/01022** (2013.01 - EP US); **H01L 2924/01029** (2013.01 - EP US); **H01L 2924/0103** (2013.01 - EP US); **H01L 2924/01033** (2013.01 - EP US); **H01L 2924/01047** (2013.01 - EP US); **H01L 2924/01058** (2013.01 - EP US); **H01L 2924/01078** (2013.01 - EP US); **H01L 2924/01079** (2013.01 - EP US); **H01L 2924/01082** (2013.01 - EP US); **H01L 2924/014** (2013.01 - EP US); **H01L 2924/12042** (2013.01 - EP US); **H01L 2924/15747** (2013.01 - EP US); **H05K 3/244** (2013.01 - EP US); **H05K 3/3473** (2013.01 - EP US)

Citation (search report)

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- [X] DATABASE WPI Section Ch Week 7435, Derwent World Patents Index; Class M11, AN 74-62624V, XP002100856
- [A] PATENT ABSTRACTS OF JAPAN vol. 009, no. 145 (C - 287) 20 June 1985 (1985-06-20)
- [A] MARUYAMA: "Functional plating", 1984, INDUSTRIAL DAILY NEWS CO. LTD, TOKYO, XP002100855

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Designated contracting state (EPC)

DE GB

DOCDB simple family (publication)

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DOCDB simple family (application)

EP 98115964 A 19970130; AU 1556297 A 19970130; DE 69720435 T 19970130; EP 97901777 A 19970130; JP 9700209 W 19970130; KR 19970706859 A 19970930; US 93051497 A 19970930